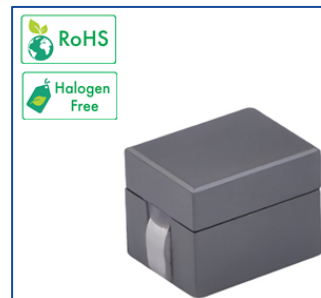
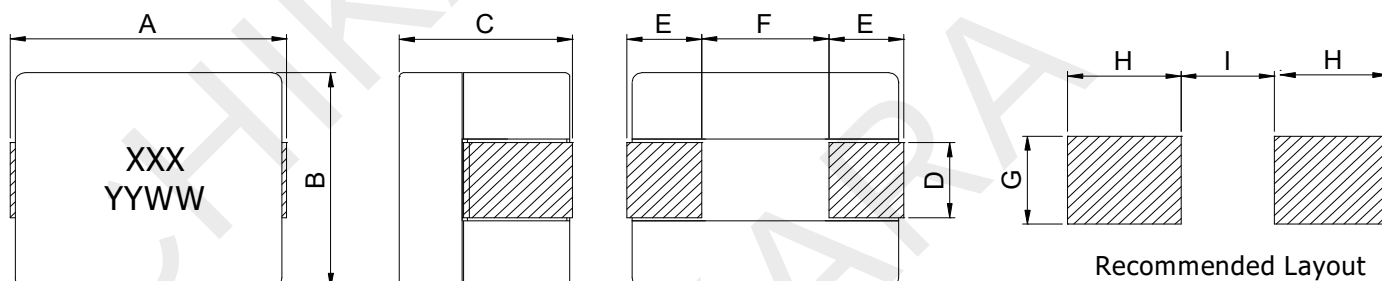


Features

- Magnetically shielded construction
- Storage temperature range:-55°C to + 130°C
- Operating temperature range:-55°C to + 130°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:1000pcs. Per 13-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



A	B	C	D	E	F	G	H	I
10.0Max.	7.0Max.	5.0Max.	2.7±0.2	1.6±0.2	6.1±0.3	3.5	2.5	5.0

Part Number Description

SP20 - 100050 R10 L
① ② ③ ④

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic

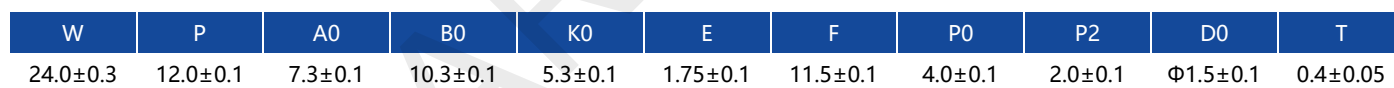


Electrical Characteristic

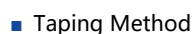
Part Number	Inductance L0(uH)	DCR (mΩ)±7%	Isat ¹ (A)Typ.@25°C	Isat ² (A)Typ.@45°C	Isat ³ (A)Typ.@100°C	Irms (A)Typ.
SP20-100050R10L	0.10±15%	0.28	72.0	65.0	63.0	34
SP20-100050R12L	0.12±15%	0.28	57.0	56.0	49.0	34
SP20-100050R13L	0.13±15%	0.28	56.0	54.0	48.0	34
SP20-100050R15L	0.15±15%	0.28	55.0	52.0	44.0	34
SP20-100050R20L	0.20±15%	0.28	36.0	33.0	27.0	34
SP20-100050R30M	0.30±20%	0.28	22.0	20.0	16.0	34

- Test frequency and voltage:100KHz,0.1Vrms.
- All test data referenced to 25°C ambient(unless otherwise noted).
- Saturation current(Isat¹&Isat²&Isat³) will cause L0 to drop approximately 20%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It' s suggested to verify the temperature rise of the component under the real operation application conditions.

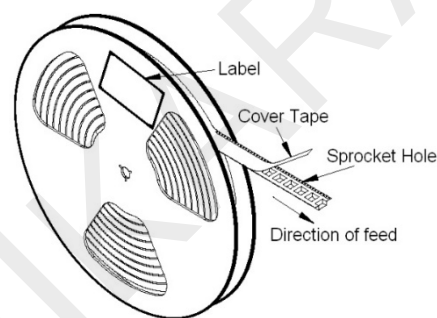
- Carrier Tape (Unit:mm)



A	B	C	D
$\Phi 330 \pm 1.0$	28.9Max.	$\Phi 100 \pm 1.0$	24.5 ± 0.5



Peel-off strength	Peel-off angle	Peel-off speed
F=0.1N~1.3N	165°~180°	300mm/min.



✖ Packing is referred to the international standard IEC 60286-3.

Parts per reel

1000Pcs

Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (Tp)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.